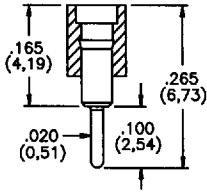
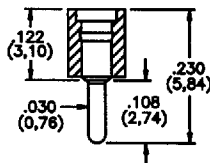


McKenzie Socket Division

SHORTER SOLDER TAIL — NO TRIMMING

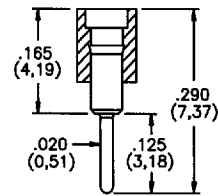


Specify Contact/Shell
018B 200 μ " Tin/200 μ " Tin
PTH = .026 \pm .003



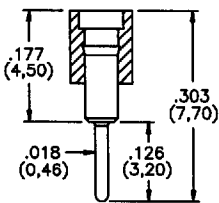
Specify Contact/Shell
185B 30 μ " Gold/200 μ " Tin
PTH = .036 \pm .003

OUR MOST POPULAR CONTACT

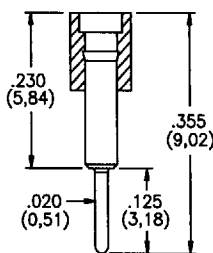


Specify Contact/Shell
001B 30 μ " Gold/200 μ " Tin
002B 30 μ " Gold/10 μ " Gold
011B 10 μ " Gold/200 μ " Tin
014B 200 μ " Tin/200 μ " Tin
016B* 30 μ " Gold/200 μ " Tin
PTH = .026 \pm .003
**CLINCHABLE SOFT BRASS*

HIGHER PCB STANDOFF

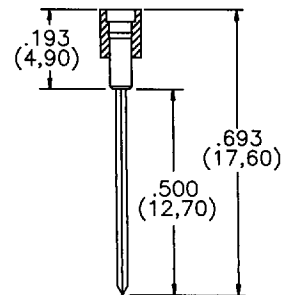


Specify Contact/Shell
248B 30 μ " Gold/10 μ " Gold
PTH = .024 \pm .003



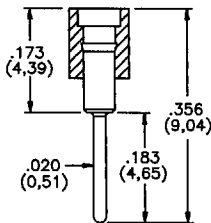
Specify Contact/Shell
040B 30 μ " Gold/10 μ " Gold
041B 30 μ " Gold/200 μ " Tin
PTH = .026 \pm .003

WIRE WRAP™ SIPs

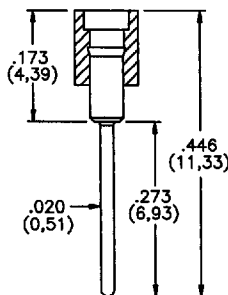


Specify Contact/Shell
410B 30 μ " Gold/200 μ " Tin
411B 30 μ " Gold/10 μ " Gold

EXTRA LONG SOLDER TAILS



Specify Contact/Shell
057B 200 μ " Tin/200 μ " Tin
054B 30 μ " Gold/200 μ " Tin
091B 30 μ " Gold/10 μ " Gold
PTH = .026 \pm .003



Specify Contact/Shell
067B 30 μ " Gold/200 μ " Tin
113B 30 μ " Gold/10 μ " Gold
PTH = .026 \pm .003

How To Order

PPC SIP - 1 x 3 2 - 0 1 1 B - R

For pins on a carrier strip begin the part number with "PPC™" or HPC for Hi-Temp Material

Product Code

Number of Rows

Number of Contacts per Row

Contact Style

Hi-Temp Material Call Out (Option)*

Contact/Shell:

Outer Shell — 1/2 Hard Brass
 Inner Contact — Beryllium Copper

Plating:

Outer Shell—Gold over 100 μ " Nickel or Tin over 100 μ " Nickel
 Inner Contact — Gold over Nickel or Tin over Nickel

Other contact and plating styles available, see Section A or consult the factory

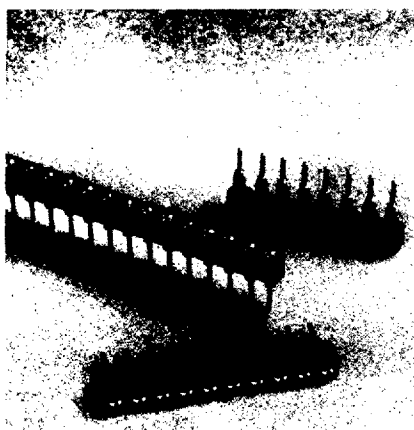
***See page B1 for Material Call Outs**

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C

Features

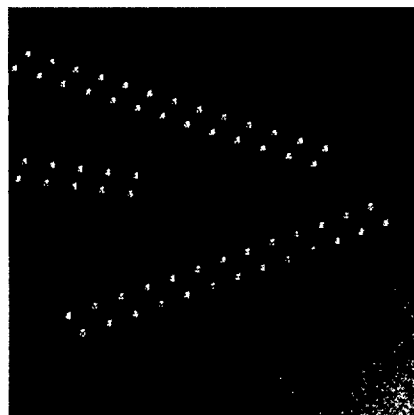
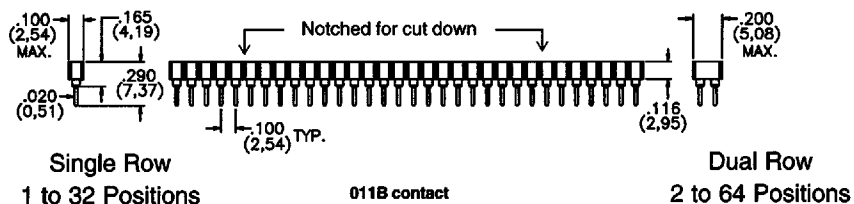
- Hi-Temp Options — IR and Vapor Phase Compatible
- X and Y Stackable
- Disposable Plastic Pin Carrier (PPC™) System Option
- Hi-Rel multifinger contact
- Insulators are notched for convenient cut down



Single Row SIP Sockets

STANDARD TEMPERATURE GLASS REINFORCED THERMOPLASTIC

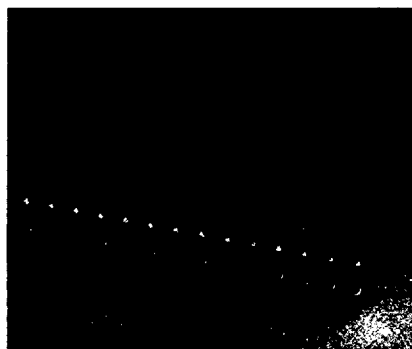
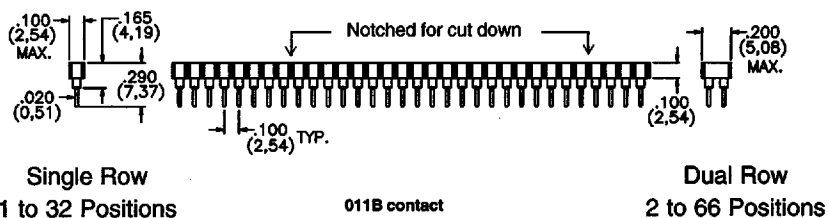
Continuous use temperature 140°C



Dual Row SIP Sockets

HI-TEMP PPS GLASS REINFORCED THERMOPLASTIC

Continuous use temperature 220°C

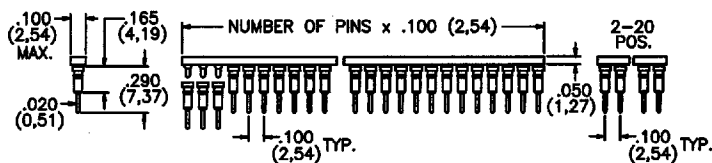


PPC™ SIP Sockets
(disposable carrier system)

Patent No. 4,420,877

PLASTIC PIN CARRIER (PPC™) SYSTEM

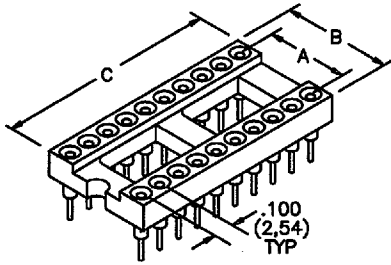
Patent #4,420,877



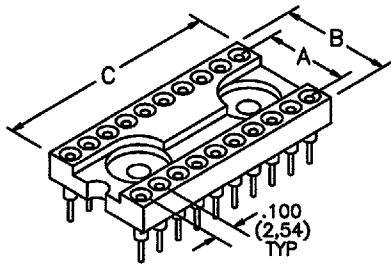
Insulators are all UL 94V-0 Rated Thermoplastic

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Insulator Options



OPEN FRAME



CLOSED FRAME

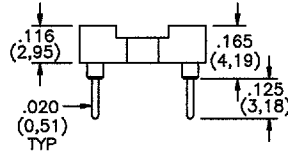
Insulators are
UL 94V-0 Rated
Thermoplastic



AVAILABLE

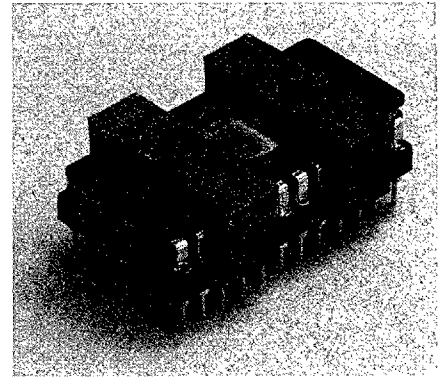
See page B1 for Hi-Temp Options

OUR MOST POPULAR CONTACT



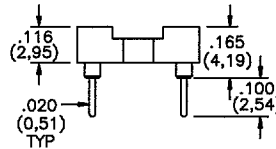
Specify	Contact/Shell
001B	30μ" Gold/200μ" Tin
002B	30μ" Gold/10μ" Gold
011B	10μ" Gold/200μ" Tin
014B	200μ" Tin/200μ" Tin
016B*	30μ" Gold/200μ" Tin
PTH =	.026 ± .003

*CLINCHABLE SOFT BRASS

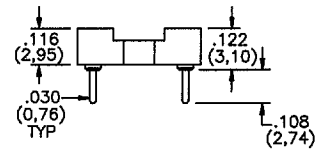


IC Retention DIP Clamps See Page B19

SHORTER SOLDER TAIL — NO TRIMMING

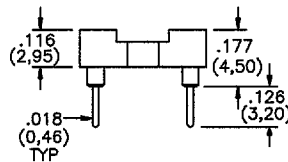


Specify	Contact/Shell
018B	200μ" Tin/200μ" Tin
PTH =	.026 ± .003

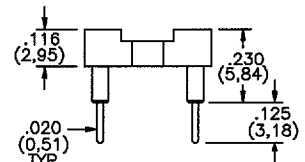


Specify	Contact/Shell
185B	30μ" Gold/200μ" Tin
PTH =	.036 ± .003

HIGHER PCB STANDOFF



Specify	Contact/Shell
248B	30μ" Gold/10μ" Gold
PTH =	.024 ± .003



Specify	Contact/Shell
040B	30μ" Gold/10μ" Gold
041B	30μ" Gold/200μ" Tin
PTH =	.026 ± .003

Contact/Shell:

Inner Contact — Beryllium Copper
Outer Shell — 1/2 Hard Brass

Plating:

Outer Shell — Gold over 100μ" Nickel or Tin over 100μ" Nickel
Inner Contact — Gold over 50μ" Nickel or Tin over 100μ" Nickel

Other contact and plating styles available, see Section A or consult the factory

Material Specifications



McKenzie Socket Division

INSULATORS	UL*	CONTINUOUS USE** TEMPERATURE	HEAT DEFLECTION** TEMPERATURE (@264 psi)
Hi-Temp - Vapor Phase and IR Compatible			
Polyimide Laminate (H), Glass Reinforced	94V-0	250°C	270°C
Fortron (PPS), (R), 40% Glass Reinforced	94V-0	220°C	260°C
Tefzel HT2004 (EPTFE),			
4% Glass Reinforced	94V-0		
8% Glass Reinforced	94V-0		
25% Glass Reinforced	94V-0	200°C	210°C
Vectra, C130 (LCP), (V)	94V-0	200°C	243°C
FR-4 Glass Epoxy (F)	94V-0	140°C	149°C
Standard Temp-Wave Solder Compatible			
Tefzel 280 (ETFE)	94V-0	150°C	74°C
Valox Polyester (420-SE0) (PBT)			
30% Fiberglass	94V-0	140°C	204°C
Zytel FR50, 25% Glass Reinforced Nylon	94V-0	130°C	240°C

*UL Flammability rating

** Typical value as defined by raw material supplier.

OUTER SHELL AND TERMINAL MATERIALS – Screw Machine Sockets

Brass - Alloy 360, 1/2 hard, per QQ-B-626

Phosphor Bronze - Alloy 544 (B2), hard, per QQ-B-750, Comp. B

INNER CONTACT MATERIALS – Screw Machine Sockets

Beryllium Copper (BeCu) - Alloy 172, heat treated, per QQ-C-533

Beryllium Nickel (BeNi) - Alloy 440, heat treated

OUTER SHELL AND TERMINAL PLATINGS – Screw Machine Sockets

200µ" (nominal) BRIGHT ACID TIN per MIL-T-10727, Type 1 over 100µ" (nominal) Nickel per QQ-N-290

10µ" (nominal) GOLD per MIL-G-45204, Type 1 GRADE C, over 100µ" (nominal) Nickel per QQ-N-290

50µ" (nominal) GOLD per MIL-G-45204, Type 1 GRADE C, over 100µ" (nominal) Nickel per QQ-N-290

200µ" (nominal) TIN/LEAD (93%/7%) per MIL-P-81728, Type 1 over 100µ" (nominal) Nickel per QQ-N-290

INNER CONTACT PLATINGS – Screw Machine Sockets

10µ" (nominal) GOLD per MIL-G-45204, Type 1, GRADE C, over 50µ" (nominal) Nickel per QQ-N-290

30µ" (nominal) GOLD per MIL-G-45204, Type 1, GRADE C, over 50µ" (nominal) Nickel per QQ-N-290

50µ" (nominal) GOLD per MIL-G-45204, Type 1, GRADE C, over 50µ" (nominal) Nickel per QQ-N-290

All McKenzie
Molded Insulators



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X

PERFORMANCE CHARACTERISTICS* — Screw Machine Sockets

Parameter	Value
Contact Resistance	<10 milliohms per contact
Contact Capacitance	0.3 pF
Contact Current Rating (for 10°C temperature rise)	3 A except for #6 (10) which is 2 A
Insulation Resistance (@ 500 V DC)	10,000 megaohms (min)
Contact Operating Temperature Range	-55°C to +150°C (BeCu) -55°C to +225°C (BeNi)
Dielectric Withstanding Voltage	1000 VAC
Rated Voltage	100 V AC
Durability	1000 cycles (min) @ 10 milliohms maximum change
Inner Contact Retention in Shell	7.5 lbs (3360 grams) minimum
Shell Retention force in Insulator (PGA's/DIP's)	10lbs (4480 grams) minimum

TEST CONDITIONS

Test	Results
Thermal Shock (IEC-68-2-14)	<2 milliohms change in contact resistance after 4 cycles (-10°C to +85°C)
Vibration (MIL-S-83505)	No electrical discontinuities or mechanical damage (10-2000Hz, 20G's, 1hr)
Solderability	Conforms to MIL-STD-202, Method 208
Shock (MIL-STD-202)	No discontinuities or mechanical damage (10 cycles of 200G's)
Temperature/Humidity Cycling (MIL-STD-1344)	<2 milliohms increase in contact resistance after 21 days, 40°C, 93% RH
Salt Spray (MIL-7344A)	<2 milliohms increase in contact resistance after 48 hrs, 35°C, 5% NaCl

*Unless otherwise stated

SPECIFICATIONS

When applicable, McKenzie Technology's products and procedures are designed to meet the following general specifications:

MIL-STD 105	Sampling procedures
MIL-STD 109	Quality assurance terms and definitions
MIL-STD 202	Test methods for electronic and electrical components part
MIL-STD 1130	Connections, electrical, solderless, wrapped
MIL-STD 1344	Test methods for electrical connectors
MIL-STD 45662	Calibration system requirements
MIL-I-45208A	Inspection system requirements
MIL-C-39029	General specification for contacts, electrical connectors
MIL-S-83505	General specification for sockets (lead, electronic components)
ASTM-B487-79	Measuring metal oxide coating thickness by microscopical examination of a cross section
ASTM-B567	Standard method of test for coating thickness by the Beta Backscatter principle
ASTM-A754-79	Standard method of test for coating thickness by X-ray fluorescence
MIL-M-24519	Molding plastics, electrical, thermoplastic
MIL-S-83734	Sockets, plug in electronic components, DIP, SIP, general specification for
MIL-P-13949	Plastic sheet, laminated, metal clad, general specification for